

Weekly Report for YiYu Shi's work in week7

February 27, 2006

1 Work1: Doing new experiments on thermal via insertion

I set up new experiments do compare between worstcase analysis and transient analysis. A 64x64 mesh with three via slots is used. Three kind of powers for running, suspend and sleeping states are randomly assigned for each block, with 10X difference between each of them. The results turn out that worstcase analysis would result in almost 10X overdesign with respect to the area.

2 Work2: Design PCB for chip

The main framework is ready. I have looked at www.digikey.com to search for related components. Early next week I will get the component lists ready and buy them.

3 Work3: Compile code from Jun

I have compiled and run all the codes, they are fine for the sample input.

I am reading Jun's dissertation and try to understand the codes in detail so that I can try different input to test it. I think this can be done by next week.